

Features

- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Fast Switching Speed
- ★ Green Device Available

Product Summary

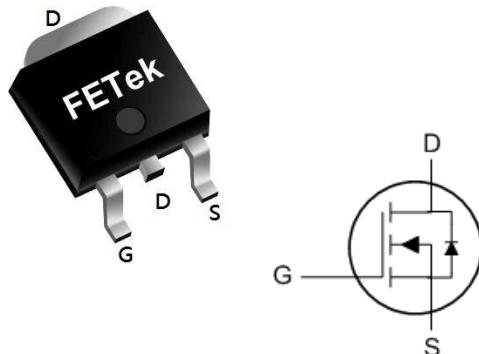


BVDSS	RDS(ON)	ID
100V	11.5mΩ	58A

Applications

- ★ High Frequency Switching and Synchronous Rectification.
- ★ DC/DC Converter.

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current ¹	58	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current ¹	36.5	A
I_{DM}	Pulsed Drain Current ²	130	A
EAS	Single Pulse Avalanche Energy ³	33	mJ
I_{AS}	Avalanche Current	15	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	73	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.7	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	100	---	---	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=20\text{A}$	---	8	11.5	$\text{m}\Omega$
	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=10\text{A}$	---	11.6	15	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=250\mu\text{A}$	1.2	---	2.4	V
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=25^\circ\text{C}$	---	---	1	uA
		$\text{V}_{\text{DS}}=80\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $\text{T}_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	0.2	0.6	1.2	Ω
Q_g	Total Gate Charge (10V)	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=20\text{A}$	---	29	---	nC
Q_g	Total Gate Charge (4.5V)		---	14	---	
Q_{gs}	Gate-Source Charge		---	6.5	---	
Q_{gd}	Gate-Drain Charge		---	5.5	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time	$\text{V}_{\text{DD}}=50\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{R}_g=3.3\Omega$, $\text{I}_D=20\text{A}$	---	8	---	ns
T_r	Rise Time		---	4	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	28	---	
T_f	Fall Time		---	6	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=50\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2550	---	pF
C_{oss}	Output Capacitance		---	305	---	
Crss	Reverse Transfer Capacitance		---	12	---	

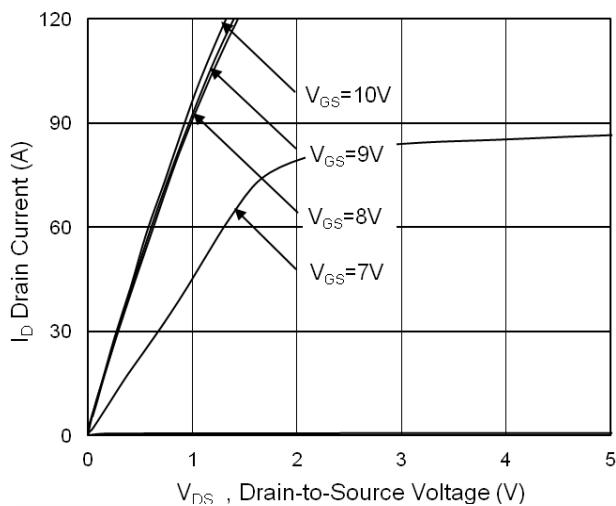
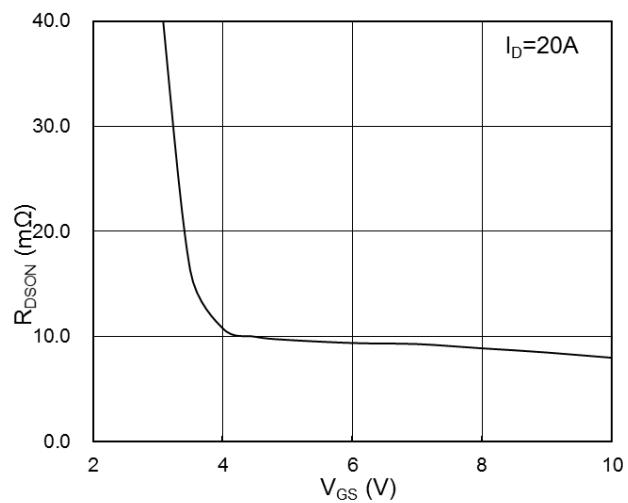
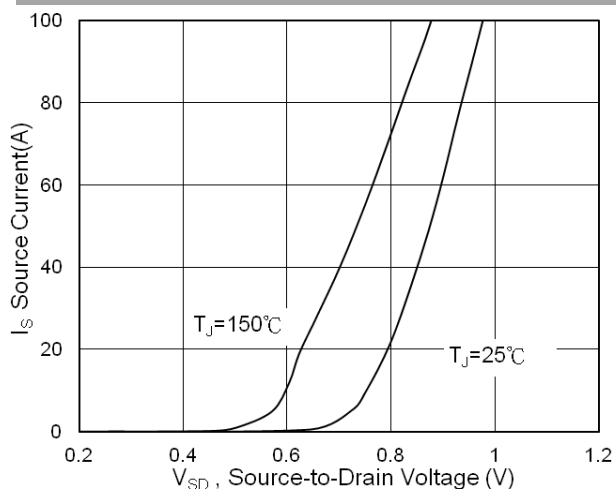
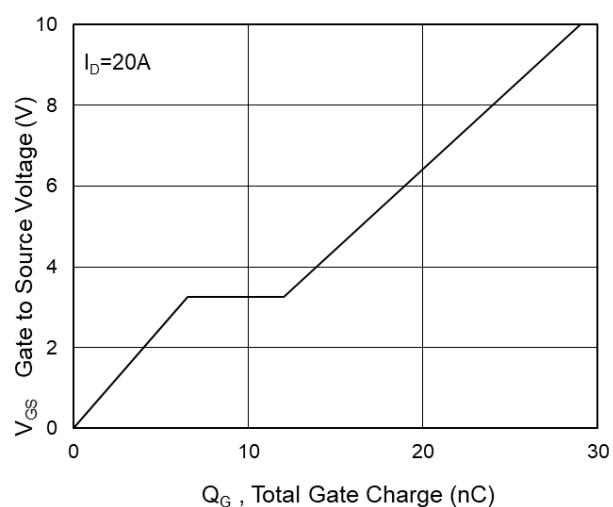
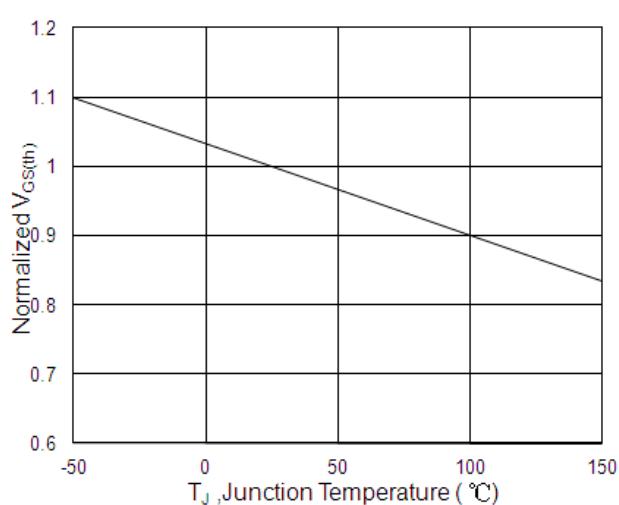
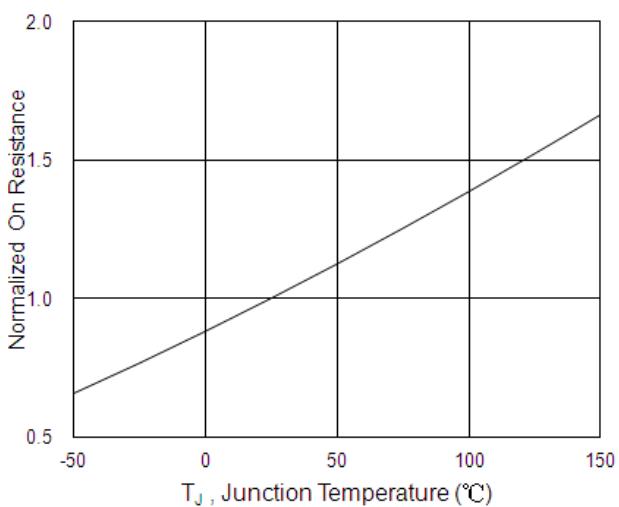
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$\text{V}_G=\text{V}_D=0\text{V}$, Force Current	---	---	58	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_s=1\text{A}$, $\text{T}_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=20\text{A}$, $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$,	---	45	---	nS
		$\text{T}_J=25^\circ\text{C}$	---	165	---	

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=25\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{L}=0.3\text{mH}$, $\text{I}_{\text{AS}}=15\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J

